

MODEL: HSB05-171711 | DESCRIPTION: HEAT SINK

FEATURES

- BGA design
- small footprint
- aluminum alloy
- black anodized finish



MODEL

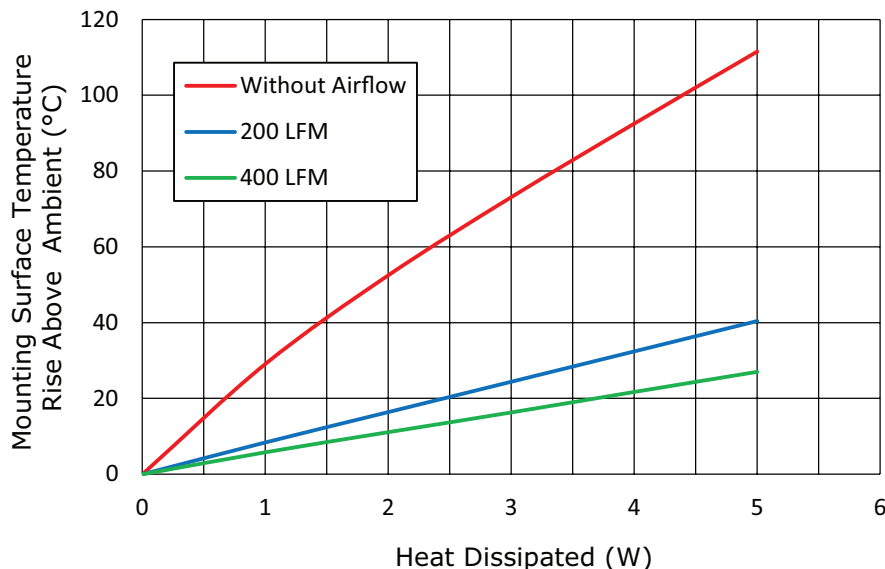
MODEL	thermal resistance ¹				power dissipation ¹
	@ 75°C ΔT, nat conv (°C/W)	@ 1 W, nat conv (°C/W)	@ 1 W, 200 LFM (°C/W)	@ 1 W, 400 LFM (°C/W)	@ 75°C ΔT, nat conv (W)
HSB05-171711	23.91	29.1	8.4	5.8	3.14

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) (°C)		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	29.1	8.4	5.8
2	52.5	16.4	11.1
3	73.1	24.4	16.3
4	92.5	32.4	21.7
5	111.5	40.2	27.0

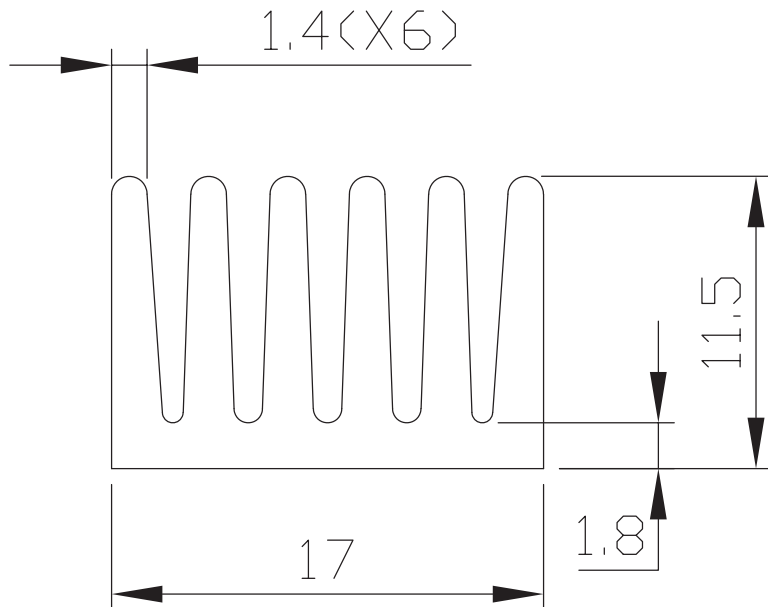
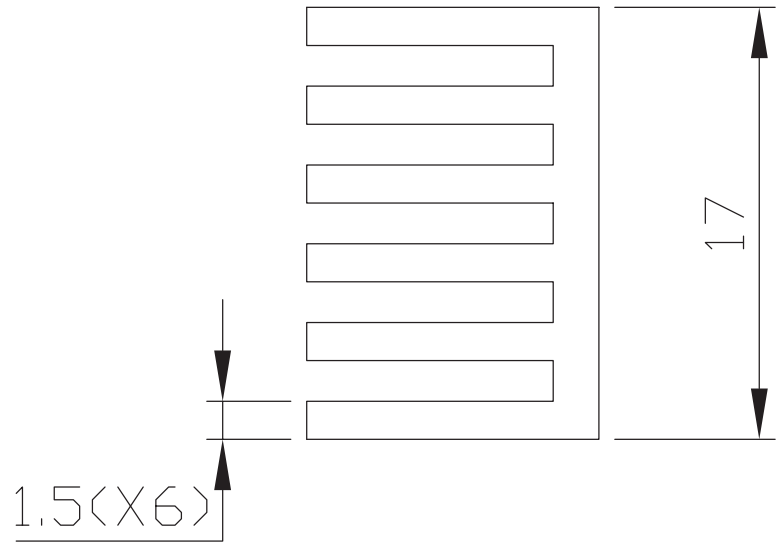
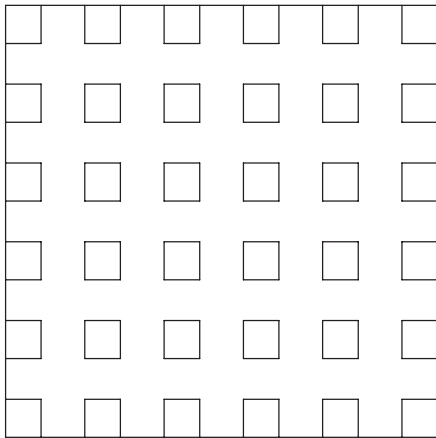
T_{hs}: "hot spot" temperature measured on the heatsink
 T_a: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ± 0.38 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	3.8 g



REVISION HISTORY

rev.	description	date
1.0	initial release	06/24/2021

The revision history provided is for informational purposes only and is believed to be accurate.

CUI DEVICES

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